



Material Content Data Sheet



Sales Product Name	BAS 40-02L E6327			Issued	25. January 2018			
MA#	MA001789470							
Package	PG-TSLP-2-1			Weight*	0.52 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.10		1046	
	noble metal	gold	7440-57-5	0.002	0.41		4057	
	inorganic material	silicon	7440-21-3	0.026	4.95	5.46	49524	54627
leadframe	non noble metal	nickel	7440-02-0	0.100	19.41	19.41	194111	194111
wire	noble metal	gold	7440-57-5	0.006	1.10	1.10	10992	10992
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		351	
	organic material	carbon black	1333-86-4	0.004	0.70		7030	
	plastics	epoxy resin	-	0.049	9.49		94893	
	inorganic material	silicondioxide	60676-86-0	0.310	60.06	70.29	600640	702914
leadfinish	noble metal	gold	7440-57-5	0.010	1.87	1.87	18678	18678
plating	noble metal	gold	7440-57-5	0.010	1.87	1.87	18678	18678
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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